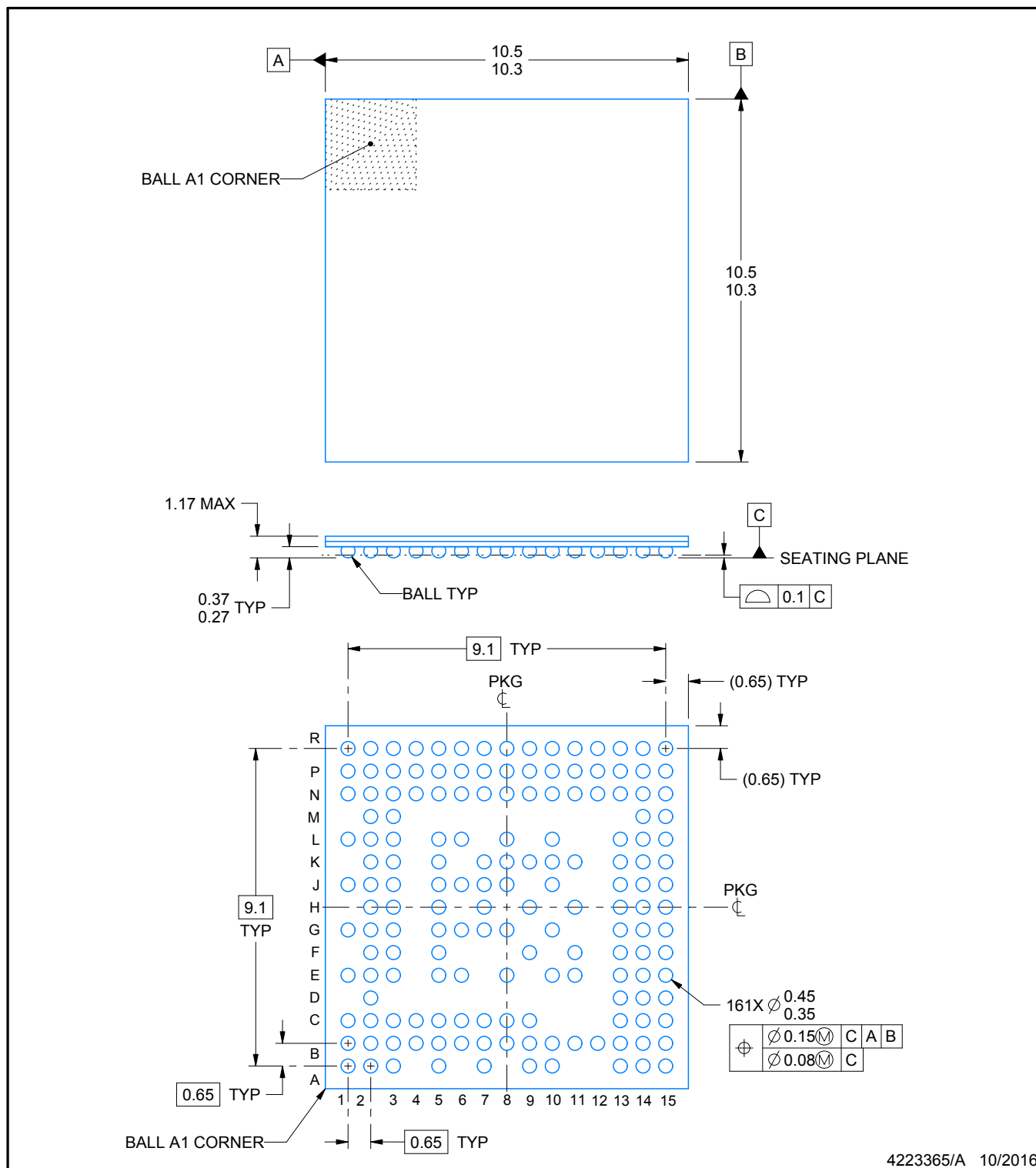
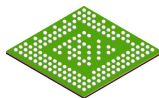


DATA BOOK
PACKAGE OUTLINE

DRAFTER:	K. SINCERBOX	DATE:	10/18/2016	DIMENSIONS IN MILLIMETERS	
DESIGNER:		DATE:		 TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS CODE IDENTITY NUMBER 01295 ePOD, ABL0161B / FCBGA, 161 BALL, 0.65 MM PITCH	
CHECKER:	T. LEQUANG & V. PAKU	DATE:	10/18/2016		
ENGINEER:	G. MORRISON	DATE:	10/18/2016		
APPROVED:	E. REY	DATE:	10/18/2016		
RELEASED:	WDM	DATE:	10/18/2016		
TEMPLATE INFO:	EDGE# 4218519	DATE:	04/07/2016	SCALE NTS	SIZE A
				4223365	REV A
					PAGE 1 OF 5



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NOTES:

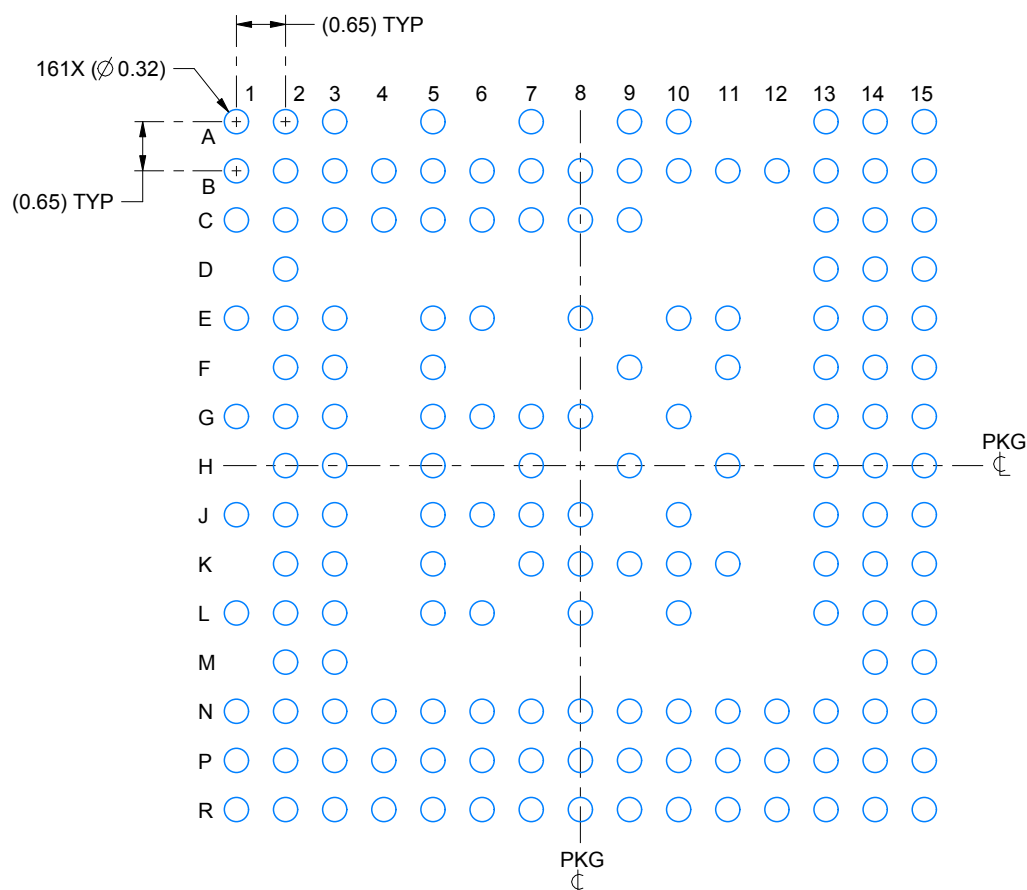
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

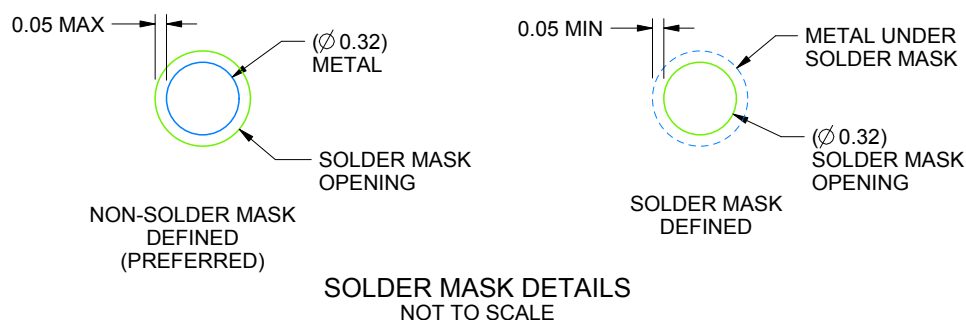
ABL0161B

FCBGA - 1.17 mm max height

PLASTIC BALL GRID ARRAY



LAND PATTERN EXAMPLE
SCALE:10X



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NOTES: (continued)

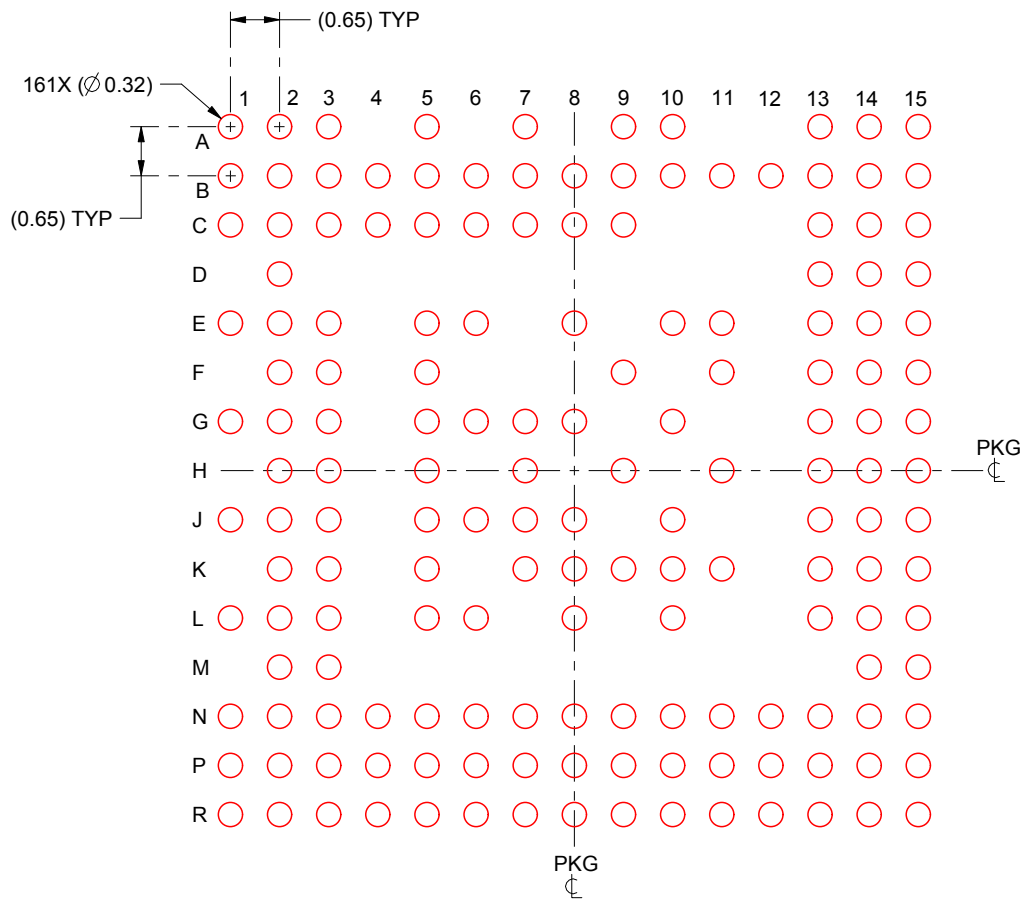
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For information, see Texas Instruments literature number SPRAA99 (www.ti.com/lit/spraa99).

EXAMPLE STENCIL DESIGN

ABL0161B

FCBGA - 1.17 mm max height

PLASTIC BALL GRID ARRAY



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE:10X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2161394	10/18/2016	G. MORRISON / K. SINCERBOX